## ABSTRACT

## MULTIPLE-HEAD WIRE-BONDING SYSTEM

The invention provides a wire-bonding apparatus for forming electrical connections between a semiconductor chip and a leadframe, comprising a plurality of bond-heads associated with a plurality of work holders on said wire bonding apparatus for holding a plurality of leadframes, wherein each bond-head of the apparatus is capable of independent bonding operation simultaneously with the other bond-heads, without synchronization of movement with the other bond-heads.

(FIG. 3)



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